

Application No. 10/017,942

AMENDMENTS TO THE CLAIMS

1. (Currently Amended) A method of packaging electronic devices that operate based on acoustic waves, comprising the steps of:

providing a cap wafer having ~~a~~an unetched cap wafer surface;

~~lithographically forming raised ridges on~~in the cap wafer surface by removing material from the unetched cap wafer surface between lithographically defined areas of the unetched cap wafer surface to form an etched cap wafer surface having the raised ridges extending therefrom~~so that the raised ridges are a contiguous part of said cap wafer, the raised ridges formed so as to have a height extending above the cap wafer surface;~~

printing a glass frit material on the raised ridges; and

bonding, via said glass frit material at each raised ridge, the unetched cap wafer surface to a substrate surface containing electronic devices,

each raised ridge using surface tension to hold the glass frit to a higher and thinner frit line width dimension, and to prevent lateral flow of the glass frit, than if the frit were deposited directly on a flat cap wafer surface without lithographically formed raised ridges.

2. (Cancel)

3. (Cancel)

4. (Cancel)

5. (Previously Presented) The method of claim 1, wherein a linewidth of the frit is less than 125 μm .

6. (Cancel)

7. (Previously Presented) The method of claim 1, wherein bonding areas when the raised ridges are bonded form a continuous perimeter around the device, so that a hermetic seal is formed.

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